



Semiconductor Device Type: EEX TQFP_100_14x14x1mm_SnPb						Package Homogeneous Materials				
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	300.79	(mg) Total	Mold Compound	% of Total Weight	56.82
Solid Epoxy Resin-1	Trade Secret	Mold Compound	2.56	13.54	25569	CEL 9240HF10AK-G1	Solid Epoxy Resin-1	Trade Secret	4.50	
Solid Epoxy Resin-2	Trade Secret	Mold Compound	3.69	19.55	36933		Solid Epoxy Resin-2	Trade Secret	6.50	
Hardener	Trade Secret	Mold Compound	3.41	18.05	34092		Hardener	Trade Secret	6.00	
Carbon Black	1333-86-4	Mold Compound	0.28	1.50	2841		Carbon Black	1333-86-4	0.50	
Amorphous Silica	60676-86-0	Mold Compound	46.88	248.15	468764		Amorphous Silica	60676-86-0	82.50	
Copper	7440-50-8	Leadframe	36.20	191.61	361959	Total 100.00				
Magnesium	7439-95-4	Leadframe	0.06	0.33	630					
Nickel	7440-02-0	Leadframe	1.15	6.09	11499	209.90	(mg) Total	Leadframe	% of Total Weight	39.65
Silicon	7440-21-3	Leadframe	0.26	1.37	2597	C7025	Copper	7440-50-8	91.29	
Silver	7440-22-4	Leadframe	1.98	10.50	19826		Magnesium	7439-95-4	0.16	
Silicon	7440-21-3	Die	1.35	7.13	13478		Nickel	7440-02-0	2.90	
Silver Flake	7440-22-4	Epoxy	0.14	0.75	1424		Silicon	7440-21-3	0.66	
Epoxy Acylate	15625-89-5	Epoxy	0.01	0.07	141		Silver	7440-22-4	5.00	
Substituted Polyamine	68490-66-4	Epoxy	0.004	0.02	38	Total 100.00				
Bisphenol F	28064-14-4	Epoxy	0.02	0.10	189					
2-Ethylhexyl Glycidyl Ether	2461-15-6	Epoxy	0.01	0.05	94	7.13	(mg) Total	Die	% of Total Weight	1.35
Copper	7440-50-8	Wire	0.55	2.90	5487			Silicon	7440-21-3	100.00
Palladium	7440-05-3	Wire	0.02	0.09	176	Total 100.00				
Tin	7440-31-5	External Plating	1.26	6.64	12551					
Lead	7439-92-1	External Plating	0.17	0.91	1711	1.00	(mg) Total	Epoxy	% of Total Weight	0.19
TOTALS: 529.37 mg Total Mass			100.00	529.37	1,000,000	YZBOND 8143	Silver Flake	7440-22-4	75.50	
							Epoxy Acylate	15625-89-5	7.50	
							Substituted Polyamine	68490-66-4	2.00	
							Bisphenol F	28064-14-4	10.00	
							2-Ethylhexyl Glycidyl Ether	2461-15-6	5.00	
						Total 100.00				
						3.00	(mg) Total	Wire	% of Total Weight	0.57
						NMC EX1 PD COAT CU WIRE (2KM)	Copper	7440-50-8	96.90	
							Palladium	7440-05-3	3.10	
						Total 100.00				
						7.55	(mg) Total	External Plating	% of Total Weight	1.43
						SnPb	Tin	7440-31-5	88.00	
							Lead	7439-92-1	12.00	
						Total 100.00				

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